

HY-LINE Power Components Vertriebs GmbH Inselkammerstr. 10 D-82008 Unterhaching © +49 89/ 614 503 -10



T-Series IGBT Modules – NX-Type

The Mitsubishi Electric 7th Generation NX-Type IGBTs greatly simplify the design of medium power inverters for various applications like industrial drives, wind power, solar power and UPS. Features such as an industry standard low profile package, significantly improved thermal impedance and very low loss, 7th Generation CSTBT™ technology facilitate a very efficient, economical and robust inverter design.

The NX-Type line-up has been expanded up to 1000A/1200V and all new 1700V and 650V line-up of dual modules to suit a wider power range of applications. Design effort is minimized as the 7th Generation NX-Type employs the same standard packaging and features previously introduced for the 5th and 6th Generation NX-Type. The newly developed SLC-Technology of the 7th Generation NX-Type enables the design of inverters with higher output current, higher power density and improved reliability in both power and temperature cycling

Product Advantages

- Low-loss 7th generation CSTBT™
- SLC package technology
- ☐ T_{i.max} of 175°C for switching operation
- High power density
- Superior thermal cycling capability
- Low-profile package
- Integrated Thermistor

er density and improved reliability in both power and temperature cycling.						
User benefits	Achieved by					
Extended module life time	 Highest thermal cycling capability by Insulated Metal Baseplate (IMB) 					
Reduction of assembly costs	Optional PressFit terminalsproduction lot-independant paralleling capability					
Compactness and extended power range	 Low loss 7th gen. Chipset Low thermal resistance Rth(j-c) Reduced package inductance by single pattern layout 					
Scalability of power classes	 full power rating line-up of 650V, 1200V and 1700V modules 					

Circuit		Topology	Package outline	Package size	650V	1200V	1700V
2in1	D			62mm x 152mm 114mm x 110mm	300A 450A 600A	225A 300A 450A 600A 800A 1000A	225A 300A 450A 600A
6in1	Т		and the state of t	62mm x 122mm	100A 150A 200A	100A 150A 200A	100A 150A
7in1	R			62mm x 122mm	150A 200A	100A 150A	
CIB	M	VI	The same of the sa	45mm x 107.5mm	50A 75A 100A	35A 50A 75A 75A	
			62mm x 122mm	100A 150A	100A 150A		



Industrial











SLC (SoLid Cover)-Technology

SLC-Technology is a newly developed package technology combining a resin-insulated metal baseplate and hard direct potting resin.

The **IMB** (Insulated Metal Baseplate) combines an electrically insulating resin layer with a top and bottom side copper layer by direct bonding, thus eliminating the substrate solder layer and the baseplate.

Less layers and matched thermal expansion coefficients lead to high thermal cycling capability, exceeding several times the conventional capability. At the same time, the thermal resistance at same chip size is reduced by 30% compared to conventional modules having Aluminium-Oxide insulation.

The SLC concept utilizes one common substrate instead of multiple ceramic substrates. This approach expands the effective area available for mounting chips and eliminates wire bond interconnections.

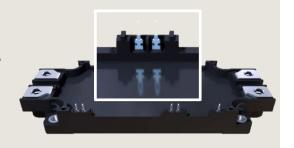
The top side circuit pattern thickness could be significantly enlarged. This es reducing the electrical resistance and or allowing to shrink the pattern size. Hence, the IMB is a key element of the SLC-Technology for high power density and low stray inductance.

Conventional Technology SLC-Technology

new

User-friendly design features

The NX-Type of 7th Generation IGBT modules line-up contains press-fit as well as solder pin types. The newly developed "needle eye"-pin type has a self adjusting shape for easy assembly.



Mitsubishi Electric Europe B.V. (European Headquarters) - Semiconductor European Business Group -

Mitsubishi-Electric-Platz 1 / D-40882 Ratingen Phone +49 (0) 2102 486 0

+49 (0) 2102 486 7220

www.MitsubishiElectric.com www.mitsubishichips.eu



